

1            98.    The method as recited in claim 15, wherein the reflowable material is the  
2    only material that contacts the metallization and the pad after the reflowing.

1            99.    The method as recited in claim 15, wherein the reflowable material is the  
2    only conductor external to the chip that contacts the pad after the reflowing.

1            100.    The method as recited in claim 25, wherein the solder joint extends  
2    continuously between the first and second surfaces in the via hole.

1            101.    The method as recited in claim 25, wherein the solder joint is the only  
2    material in the via hole that contacts the metallization.

1            102.    The method as recited in claim 25, wherein the solder joint is the only  
2    material in the via hole that contacts the pad.

1            103.    The method as recited in claim 25, wherein the solder joint is the only  
2    material that contacts the metallization and the pad.

1            104.    The method as recited in claim 25, wherein the solder joint is the only  
2    conductor external to the chip that contacts the pad.

1            105.    The method as recited in claim 50, wherein the solder joint extends  
2    continuously between the first and second surfaces in the via hole.

1            106.    The method as recited in claim 50, wherein the solder joint is the only  
2    material in the via hole that contacts the metallization.

1            107.    The method as recited in claim 50, wherein the solder joint is the only  
2    material in the via hole that contacts the pad.

1            108.    The method as recited in claim 50, wherein the solder joint is the only  
2    material that contacts the metallization and the pad.

1            109.    The method as recited in claim 50, wherein the solder joint is the only  
2    conductor external to the chip that contacts the pad.

1            110.    The method as recited in claim 55, wherein the solder joint extends  
2    continuously between the first and second surfaces in the via hole.

1            111.    The method as recited in claim 55, wherein the solder joint is the only  
2    material in the via hole that contacts the metallization.

1            112.    The method as recited in claim 55, wherein the solder joint is the only  
2    material in the via hole that contacts the pad.

1            113.    The method as recited in claim 55, wherein the solder joint is the only  
2    material that contacts the metallization and the pad.

1            114.    The method as recited in claim 55, wherein the solder joint is the only  
2    conductor external to the chip that contacts the pad.

1            115.    The method as recited in claim 60, wherein the solder joint extends  
2    continuously between the first and second surfaces in the via hole.

1            116.    The method as recited in claim 60, wherein the solder joint is the only  
2    material in the via hole that contacts the metallization.

1            117.    The method as recited in claim 60, wherein the solder joint is the only  
2    material in the via hole that contacts the pad.

*C1 and*  
1 118. The method as recited in claim 60, wherein the solder joint is the only  
2 material that contacts the metallization and the pad.

1 119. The method as recited in claim 60, wherein the solder joint is the only  
2 conductor external to the chip that contacts the pad.

---